Copper Layer Count: 2 Board Thickness: 1.6000 mm

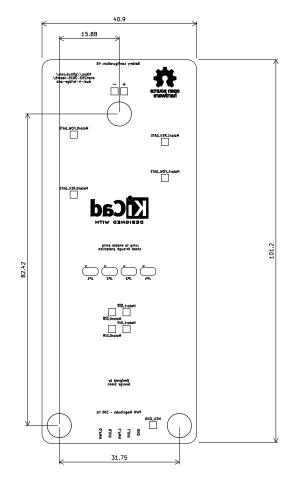
Board overall dimensions: $40.8940 \text{ mm} \times 101.4730 \text{ mm}$

Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.2500 mm

Copper Finish: None Impedance Control: No Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



George Sleer	n	
Team 5		
Sheet:		
File: dual-h	-bridge.kicad_pcb	
Title: Dua	al H—Bridge	
Size: A4	Date: 2025-07-05	Rev: v2.0.1

Copper Layer Count: 2 Board Thickness: 1.6000 mm

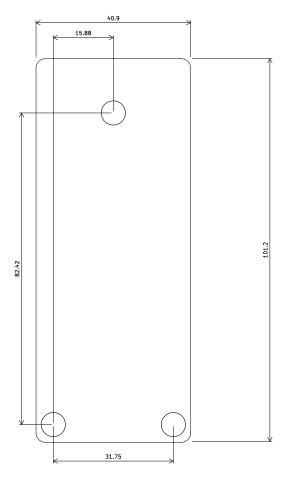
Board overall dimensions: $40.8940 \text{ mm} \times 101.4730 \text{ mm}$

Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.2500 mm

Copper Finish: None Impedance Control: No Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



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Team 5			
Sheet:			
File: dual-h-bridge.kicad_pcb			
Title: Dual	H–Bridge		
Size: A4	Date: 2025-07-05	Rev: v2.0.1	
KiCad E.D.A. 9.	ld: 2/4		

Copper Layer Count: 2 Board Thickness: 1.6000 mm

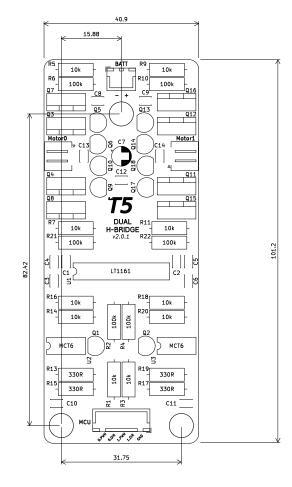
Board overall dimensions: $40.8940 \text{ mm} \times 101.4730 \text{ mm}$

Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.2500 mm

Copper Finish: None Impedance Control: No Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
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F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



George Sleen
Team 5

Rev: v2.0.1

Sheet: File: dual-h-bridge.kicad_pcb

Title: Dual H-Bridge
Size: A4 Date: 2025-07-05

KiCad E.D.A. 9.0.2 Id: 3/4

3 4 5

Copper Layer Count: 2 Board Thickness: 1.6000 mm

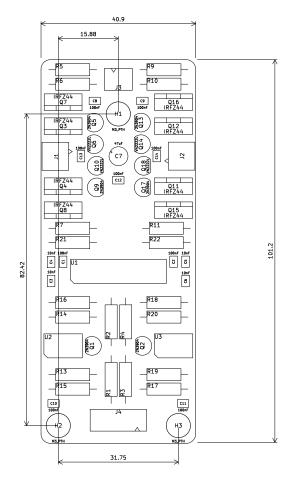
Board overall dimensions: $40.8940 \text{ mm} \times 101.4730 \text{ mm}$

Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.2500 mm

Copper Finish: None Impedance Control: No Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
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B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



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Team 5

Sheet:
File: dual-h-bridge.kicad_pcb

Title: Dual H-Bridge

Size. Mr. Debr. 2005, 07, 05

 Size: A4
 Date: 2025-07-05
 Rev: v2.0.1

 KiCad E.D.A. 9.0.2
 Id: 4/4